

MCU 16-bit/32-bit LPC2300 ARM7TDMI-S RISC 512KB Flash 3.3V

Manufacturers	NXP Semiconductor
Package/Case	LQFP-100
Product Type	Embedded Processors & Controllers
RoHS	
Lifecycle	



Images are for reference only

Please submit RFQ for LPC2368FBD100 or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

LPC2368FBD100 is a microcontroller chip from NXP Semiconductors, which is a member of the LPC2000 series.

Features

- 16/32-bit ARM7TDMI-S CPU core running at up to 72 MHz clock frequency
- 512 KB on-chip flash memory and 98 KB on-chip SRAM
- In-system programming (ISP) and in-application programming (IAP) via on-chip boot-loader software
- Two 10-bit ADCs, two DACs, and multiple PWM channels
- Multiple serial communication interfaces including UART, SPI, I2C, and CAN
- On-chip Ethernet MAC, USB 2.0 full-speed interface, and external memory controller
- Multiple power-saving modes and a range of operating temperatures (-40 to +85 °C)

Application

- Industrial automation and control
- Robotics
- Building automation
- Medical devices
- Automotive electronics
- Consumer electronics
- Security and access control systems

DOU YEE
DY3008-803

NXP SEMICONDUCTORS
MADE IN TAIWAN

(33T) PUID: 07SSUP27GM000
(32T) ORIG: N371
(31T) PMC: ZSD
(31P) MSL: 3240
MSL: 3200

(1T) LOT: SAT334

(9B) DATE: 1527

(Q) QTY: 10

(30P) TYPE: LPC2346FD100

(1P) CODENO: 9352 R2461SS1

HALOGEN FREE

ROHS COMPLIANT



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
**ELECTROSTATIC
SENSITIVE
DEVICES**



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

For MSL

see

barcodes

label

1. Calculated shelf life in sealed bag: 12 months at -40°C and $< 90\%$ relative humidity (RH).
2. Peak Package body temperature: _____ $^{\circ}\text{C}$
(if blank, see adjacent barcode label)
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:
 - a) Mounted within the time corresponding to the MSL at factory conditions of $\leq 30^{\circ}\text{C}/60\%$ RH:

LEVEL 2 - 1 year	LEVEL 4 - 72 hours
LEVEL 2a - 4 weeks	LEVEL 5 - 48 hours
LEVEL 3 - 168 hours	LEVEL 5a - 24 hours
LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours.	
 - b) Stored per IPC/JEDEC J-STD-033.
4. Devices require baking, before mounting if:
 - a) Humidity Indicator Card reads $>10\%$ for level 2a - 5a devices or $>60\%$ for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$
 - b) 3a or 3b not met.
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: _____
(if blank, see date code on barcode label)

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020



DOU YEE
DY3008-803

NXP SEMICONDUCTORS
MADE IN TAIWAN

(33T) PUID: 07SSUP527GMB000

(1T) LOT SAT534.1

(32T) ORIG N371

(31T) PMC ZSD

(31P) MSL 3/240

MSL 3/260

(9D) DATE 1527



(Q) QTY 90



(30P) TYPE LPC2368FBD100

(1P) CODENO 9352 824 61551



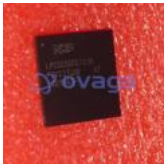
HALOGEN FREE

EU/CN RoHS COMPLIANT



ATTENTION
OBSERVE PRECAUTIONS

Related Products



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NXP Semiconductor
TFBGA296



[LPC1756FBD80](#)

NXP Semiconductor
QFP80



[LPC11C24FBD48/301](#)

NXP Semiconductor
LQFP48



[LPC2129FBD64](#)

NXP Semiconductor
LQFP-64



[LPC2387FBD100](#)

NXP Semiconductor
LQFP-100



[LPC2364FBD100](#)

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LQFP-100



[LPC2468FBD208](#)

NXP Semiconductor
LQFP-208



[LPC1764FBD100](#)

NXP Semiconductor
QFP100